

## Hermetic Al Micro-D

### Overview

These Micro-D connectors meet the same interface requirements as our other robust mil-spec compliant connectors. The controlled CTE characteristics, chemical bonding properties and polycrystalline structure of Kryoflex®, allow Qnnect to use gold plated beryllium copper contacts for excellent electrical performance and environmental characteristics.

### Technical Advantages

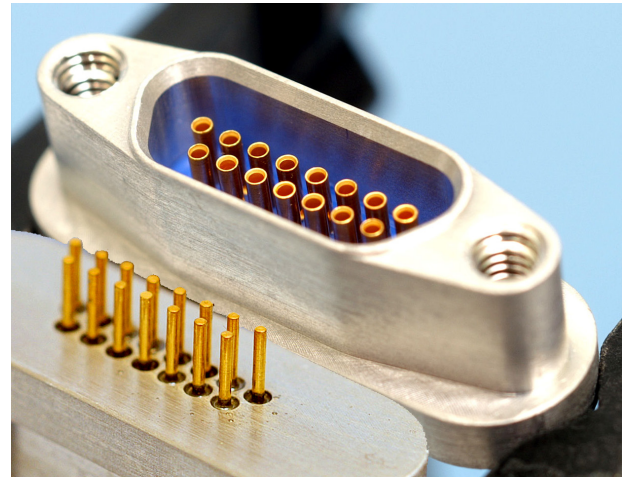
PA&E's technology is proven in the harshest environments – from deep beneath the earth's surface to deep space and even within the human body. Our all aluminum Micro-D connectors provide a unique solution for applications that require a combination of light weight, and high electrical performance.

### Applications

- Defense Aircraft
- Airborne Weapons Systems
- Launch Vehicles
- Satellites

### Materials

- Material Compatibility: Designed for Aluminum Applications
- Shell Finish Options: Chromate Conversion Coated per MIL-C-5541
- Contact Material: Beryllium Copper CDA Alloy 172/173
- Contact Finish: Nickel/Gold Plating



### Electrical

- Current Rating: Subject to Pin Configuration
- Insulation Resistance: Provides Greater Than 5,000 Megohms at 500 VDC When Tested in IAW MIL-STD-1344, Method 3003
- Dielectric Withstanding Voltage: Exhibits No Evidence of Breakdown or Flash-over When Tested in IAW MIL-STD-1344, Method 3003

### Environmental

- Operating Temperature: -55°C to 125°C
- Salt Spray Resistance: Connectors Meet Salt Spray Test in IAW MIL-STD-1344, Method 3003
- Sealing: Kryoflex Polycrystalline Ceramic

### Mechanical

- Interface: Per MIL-PRF-83513
- Number of Contacts: 9, 15, 21, 25, 31 and 37
- Leak Rate: Less Than  $1 \times 10^{-9}$  cc/sec Helium at 1 Atmospheric Differential Pressure



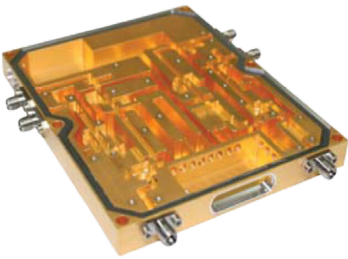
**For More Info:**  
**[qnnectnow.com](https://qnnectnow.com)**  
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## Other Products & Services:

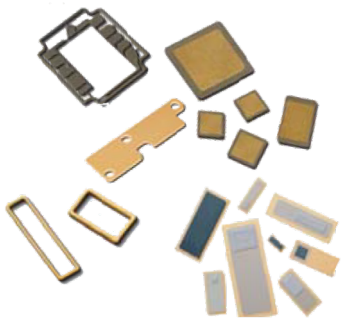
### Hermetic Electronic Packaging

We bring customers' hermetic electronic package designs to life and use unique materials and manufacturing processes to help optimize for weight savings, footprint reduction, thermal transfer and more. Our precision machining capabilities allow us to meet very tight tolerances for aluminum and titanium housings. We deliver the custom packaging solutions that ensure the electronics within those devices are unaffected by whatever extreme environmental condition they operate in.



### Enabling Components

There's more to a reliable hermetic package solution than a box and connectors and we manufacture components to ensure a module's long term viability. We produce: getters to prevent build-up of contaminants; solder preforms that aid in attaching electronic circuitry; ring frames that become integral side walls of a hermetic package; and custom thermal spreaders that ensure heat from a chip or substrate is efficiently dissipated. To top things off, we also manufacture package lids.



### Laser and Integration Services

We provide high-speed laser welding, sealing and marking with consistent accuracy. Our laser welding expertise also extends to the manufacture of custom designed/build laser welding, cutting & sealing systems for customers who wish to bring those capabilities in house.